


PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

| | | |
|-----------------------------|---|--------------------------------------|
| 1.1 Company |  | STMicroelectronics International N.V |
| 1.2 PCI No. | ADG/20/12528 | |
| 1.3 Title of PCI | Orientation of PowerFLAT 8X8 HV Package in carrier tape & Datasheet update | |
| 1.4 Product Category | Power MOSFET HV | |
| 1.5 Issue date | 2020-12-22 | |

2. PCI Team

| | |
|----------------------------------|-------------------------|
| 2.1 Contact supplier | |
| 2.1.1 Name | NEMETH KRISZTINA |
| 2.1.2 Phone | +49 89460062210 |
| 2.1.3 Email | krisztina.nemeth@st.com |
| 2.2 Change responsibility | |
| 2.2.1 Product Manager | Maurizio GIUDICE |
| 2.1.2 Marketing Manager | Paolo PETRALI |
| 2.1.3 Quality Manager | Vincenzo MILITANO |

3. Change

| | | |
|--------------------------|--|---------------------------------------|
| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location |
| General Product & Design | Modification of datasheet : Errata/error fix | ASE-WEIHAI (China), CARSEM (Malaysia) |

4. Description of change

| | | |
|--|--|---|
| | Old | New |
| 4.1 Description | PowerFLAT 8X8 HV packed in carrier tape with reference to the pin positioned at the top right. | PowerFLAT 8X8 HV packed in carrier tape with reference to the pin positioned at the top left. |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | no impact | |

5. Reason / motivation for change

| | |
|-----------------------------|---|
| 5.1 Motivation | in order to be aligned to the JEDEC/EIA specification |
| 5.2 Customer Benefit | QUALITY IMPROVEMENT |

6. Marking of parts / traceability of change

| | |
|------------------------|----------------|
| 6.1 Description | by Q.A. number |
|------------------------|----------------|

7. Timing / schedule

| | |
|--|----------------|
| 7.1 Date of qualification results | 2020-12-17 |
| 7.2 Intended start of delivery | 2021-01-10 |
| 7.3 Qualification sample available? | Not Applicable |

8. Qualification / Validation

| | | | |
|---|-------------|-------------------|--|
| 8.1 Description | | | |
| 8.2 Qualification report and qualification results | In progress | Issue Date | |

9. Attachments (additional documentations)

12528 Public product.pdf
12528 Orientation of PowerFLATTM 8X8 HV in carrier tape TOP-LEFT.pdf

| 10. Affected parts | | |
|-------------------------|-------------------------|--------------------------|
| 10. 1 Current | | 10.2 New (if applicable) |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No |
| 3527139 | STL19N60M6 | |
| 3105980 | STL33N60M6 | |
| 2729678 | STL36N55M5 | |
| 3294305 | STL45N60DM6 | |
| 3105981 | STL47N60M6 | |

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